Fast Recovery Diodes (FRD)

MA3DF46

Silicon mesa type

For high frequency recification

For plasma display panel drive

Features

- \bullet Super high speed switching characteristic (t_rr = 15 ns typ.)
- Soft recovery

Absolute Maximum Ratings $T_a = 25^{\circ}C$

0			
Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V _{RRM}	370	V
Non-repetitive peak reverse surge voltage *1	V _{RSM}	430	V
Forward current (Average) *2	I _{F(AV)}	20	А
Repetitive peak forward current *3	I _{FRM}	150	А
Non-repetitive peak forward surge current *4	I _{FSM}	100	Α
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-40 to +150	°C

Note) *1: 60 Hz half-sine wave. (If repeative, RMS voltage < 370 V)

*2: $T_{C} = 25^{\circ}C$

*3: Pulse width $< 10 \,\mu$ s. Peak value of the sine wave. (If repeative, RMS current $< 20 \,\text{A}$)

*4: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

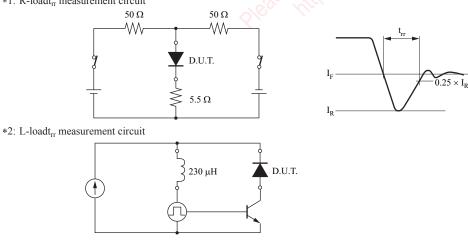
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$ Conditions Parameter Symbol Min Unit Тур Max VF $I_{\rm F} = 20 \, {\rm A}$ 1.45 V Forward voltage 1.65 Reverse current $V_{RRM} = 370 V$ 10 μΑ I_{RRM} t_{rr} *1 $I_F = 0.5 A$, $I_R = 1.0 A$, $I_{rr} = 0.25 A$ 15 23 Reverse recovery time ns t_{rr}*2 $I_F = 40 \text{ A}, \text{ di/dt} = -200 \text{ A/}\mu\text{s}, I_{IT} = I_R \times 0.5 \text{ A}$ 30 35 Thermal resistance (j-c) R_{th(j-c)} 3.0 °C/W Thermal resistance (j-a) R_{th(j-a)} 63 °C/W

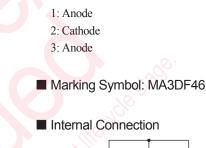
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz

3. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

4. *1: R-loadt_{π} measurement circuit





Package

TO-220D-A1

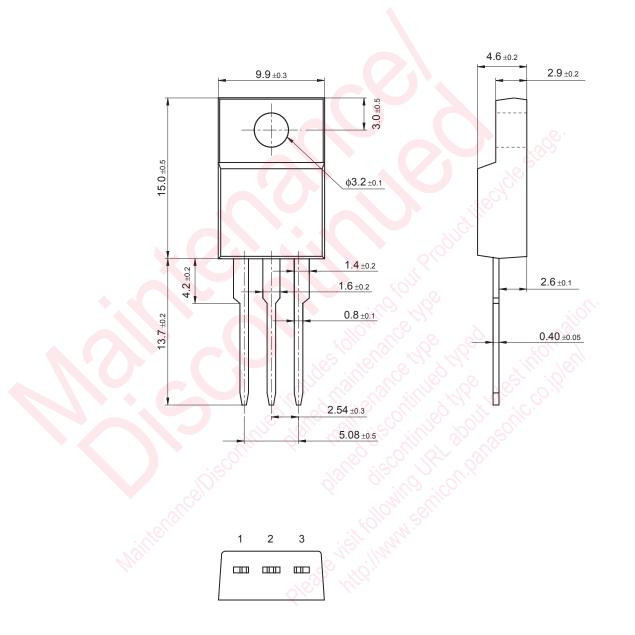
Pin Name

Code

Publication date: May 2009

TO-220D-A1

Unit: mm



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